

**INTEGRATED CIRCUITS**

# DATA SHEET

## **74AHC1G126; 74AHCT1G126** **Bus buffer/line driver; 3-state**

Product specification  
Supersedes data of 2002 Feb 15

2002 Jun 06

Philips  
Semiconductors



# PHILIPS



**Bus buffer/line driver; 3-state****74AHC1G126; 74AHCT1G126****FEATURES**

- Symmetrical output impedance
- High noise immunity
- ESD protection:
  - HBM EIA/JESD22-A114-A exceeds 2000 V
  - MM EIA/JESD22-A115-A exceeds 200 V
  - CDM EIA/JESD22-C101 exceeds 1000 V.
- Low power dissipation
- Balanced propagation delays
- Very small 5-pin package
- Output capability: standard
- Specified from –40 to +125 °C.

**DESCRIPTION**

The 74AHC1G/AHCT1G126 is a high-speed Si-gate CMOS device.

The 74AHC1G/AHCT1G126 provides one non-inverting buffer/line driver with 3-state output. The 3-state output is controlled by the output enable input pin (OE). A LOW at pin OE causes the output to assume a high-impedance OFF-state.

**QUICK REFERENCE DATA**

Ground = 0 V;  $T_{amb} = 25\text{ °C}$ ;  $t_r = t_f \leq 3.0\text{ ns}$ .

| SYMBOL            | PARAMETER                     | CONDITIONS  | TYPICAL |        | UNIT |
|-------------------|-------------------------------|---|---------|--------|------|
|                   |                               |   | AHC1G   | AHCT1G |      |
| $t_{PHL}/t_{PLH}$ | propagation delay A to Y      | $C_L = 15\text{ pF}$ ; $V_{CC} = 5\text{ V}$              | 3.4     | 3.4    | ns   |
| $C_I$             | input capacitance             |   | 1.5     | 1.5    | pF   |
| $C_{PD}$          | power dissipation capacitance | $C_L = 50\text{ pF}$ ; $f = 1\text{ MHz}$ ; notes 1 and 2 | 9       | 11     | pF   |

**Notes**

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ).

$P_D = C_{PD} \times V_{CC}^2 \times f_i + (C_L \times V_{CC}^2 \times f_o)$  where:

$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

$C_L$  = output load capacitance in pF;

$V_{CC}$  = supply voltage in Volts.

2. The condition is  $V_I = \text{GND to } V_{CC}$ .

## Bus buffer/line driver; 3-state

## 74AHC1G126; 74AHCT1G126

**FUNCTION TABLE**

See note 1.

| INPUTS |   | OUTPUT |
|--------|---|--------|
| OE     | A | Y      |
| H      | L | L      |
| H      | H | H      |
| L      | X | Z      |

**Note**

- H = HIGH voltage level;  
L = LOW voltage level;  
X = don't care;  
Z = high-impedance OFF-state.

**ORDERING INFORMATION**

| TYPE NUMBER   | PACKAGES          |      |         |          |        |         |
|---------------|-------------------|------|---------|----------|--------|---------|
|               | TEMPERATURE RANGE | PINS | PACKAGE | MATERIAL | CODE   | MARKING |
| 74AHC1G126GW  | -40 to +125 °C    | 5    | SC-88A  | plastic  | SOT353 | AN      |
| 74AHCT1G126GW | -40 to +125 °C    | 5    | SC-88A  | plastic  | SOT353 | CN      |
| 74AHC1G126GV  | -40 to +125 °C    | 5    | SC-74A  | plastic  | SOT753 | A26     |
| 74AHCT1G126GV | -40 to +125 °C    | 5    | SC-74A  | plastic  | SOT753 | C26     |

**PINNING**

| PIN | SYMBOL          | DESCRIPTION         |
|-----|-----------------|---------------------|
| 1   | OE              | output enable input |
| 2   | A               | data input A        |
| 3   | GND             | ground (0 V)        |
| 4   | Y               | data output Y       |
| 5   | V <sub>CC</sub> | supply voltage      |

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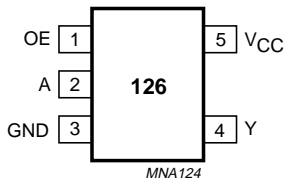


Fig.1 Pin configuration.

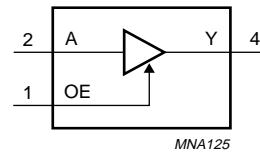


Fig.2 Logic symbol.

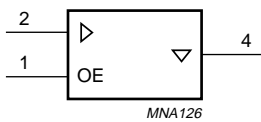


Fig.3 IEC logic symbol.

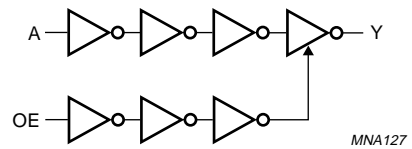


Fig.4 Logic diagram.

## Bus buffer/line driver; 3-state

## 74AHC1G126; 74AHCT1G126

## RECOMMENDED OPERATING CONDITIONS

| SYMBOL                         | PARAMETER                     | CONDITIONS                               | 74AHC1G |      |          | 74AHCT1G |      |          | UNIT |
|--------------------------------|-------------------------------|--|---------|------|----------|----------|------|----------|------|
|                                |                               |  | MIN.    | TYP. | MAX.     | MIN.     | TYP. | MAX.     |      |
| $V_{CC}$                       | supply voltage                |  | 2.0     | 5.0  | 5.5      | 4.5      | 5.0  | 5.5      | V    |
| $V_I$                          | input voltage                 |  | 0       | –    | 5.5      | 0        | –    | 5.5      | V    |
| $V_O$                          | output voltage                |  | 0       | –    | $V_{CC}$ | 0        | –    | $V_{CC}$ | V    |
| $T_{amb}$                      | operating ambient temperature | see DC and AC characteristics per device | –40     | +25  | +125     | –40      | +25  | +125     | °C   |
| $t_r, t_f (\Delta t/\Delta f)$ | input rise and fall times     | $V_{CC} = 3.3 \pm 0.3$ V                 | –       | –    | 100      | –        | –    | –        | ns/V |
|                                |                               | $V_{CC} = 5 \pm 0.5$ V                   | –       | –    | 20       | –        | –    | 20       | ns/V |

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

| SYMBOL    | PARAMETER                     | CONDITIONS                                       | MIN. | MAX. | UNIT |
|-----------|-------------------------------|--|------|------|------|
| $V_{CC}$  | supply voltage                |  | –0.5 | +7.0 | V    |
| $V_I$     | input voltage                 |  | –0.5 | +7.0 | V    |
| $I_{IK}$  | input diode current           | $V_I < -0.5$ V                                   | –    | –20  | mA   |
| $I_{OK}$  | output diode current          | $V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V; note 1 | –    | ±20  | mA   |
| $I_O$     | output source or sink current | $-0.5$ V < $V_O$ < $V_{CC} + 0.5$ V              | –    | ±25  | mA   |
| $I_{CC}$  | $V_{CC}$ or GND current       |  | –    | ±75  | mA   |
| $T_{stg}$ | storage temperature           |  | –65  | +150 | °C   |
| $P_D$     | power dissipation per package | for temperature range from –40 to +125 °C        | –    | 250  | mW   |

## Note

- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

## Bus buffer/line driver; 3-state

## 74AHC1G126; 74AHCT1G126

## DC CHARACTERISTICS

## Family 74AHC1G

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| SYMBOL          | PARAMETER                 | TEST CONDITIONS   | V <sub>CC</sub><br>(V) | T <sub>amb</sub> (°C) |      |      |      |            |      | UNIT |             |      |
|-----------------|---------------------------|---|------------------------|-----------------------|------|------|------|------------|------|------|-------------|------|
|                 |                           |   |                        | OTHER                 | 25   |      |      | -40 to +85 |      |      | -40 to +125 |      |
|                 |                           |   |                        |                       | MIN. | TYP. | MAX. | MIN.       | MAX. |      | MIN.        | MAX. |
| V <sub>IH</sub> | HIGH-level input voltage  |   | 2.0                    | 1.5                   | –    | –    | 1.5  | –          | 1.5  | –    | V           |      |
|                 |                           |   | 3.0                    | 2.1                   | –    | –    | 2.1  | –          | 2.1  | –    | V           |      |
|                 |                           |   | 5.5                    | 3.85                  | –    | –    | 3.85 | –          | 3.85 | –    | V           |      |
| V <sub>IL</sub> | LOW-level input voltage   |   | 2.0                    | –                     | –    | 0.5  | –    | 0.5        | –    | 0.5  | V           |      |
|                 |                           |   | 3.0                    | –                     | –    | 0.9  | –    | 0.9        | –    | 0.9  | V           |      |
|                 |                           |   | 5.5                    | –                     | –    | 1.65 | –    | 1.65       | –    | 1.65 | V           |      |
| V <sub>OH</sub> | HIGH-level output voltage | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = -50 µA  | 2.0                    | 1.9                   | 2.0  | –    | 1.9  | –          | 1.9  | –    | V           |      |
|                 |                           | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = -50 µA  | 3.0                    | 2.9                   | 3.0  | –    | 2.9  | –          | 2.9  | –    | V           |      |
|                 |                           | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = -50 µA  | 4.5                    | 4.4                   | 4.5  | –    | 4.4  | –          | 4.4  | –    | V           |      |
|                 |                           | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = -4.0 mA | 3.0                    | 2.58                  | –    | –    | 2.48 | –          | 2.40 | –    | V           |      |
|                 |                           | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = -8.0 mA | 4.5                    | 3.94                  | –    | –    | 3.8  | –          | 3.70 | –    | V           |      |
| V <sub>OL</sub> | LOW-level output voltage  | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = 50 µA   | 2.0                    | –                     | 0    | 0.1  | –    | 0.1        | –    | 0.1  | V           |      |
|                 |                           | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = 50 µA   | 3.0                    | –                     | 0    | 0.1  | –    | 0.1        | –    | 0.1  | V           |      |
|                 |                           | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = 50 µA   | 4.5                    | –                     | 0    | 0.1  | –    | 0.1        | –    | 0.1  | V           |      |
|                 |                           | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = 4.0 mA  | 3.0                    | –                     | –    | 0.36 | –    | 0.44       | –    | 0.55 | V           |      |
|                 |                           | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = 8.0 mA  | 4.5                    | –                     | –    | 0.36 | –    | 0.44       | –    | 0.55 | V           |      |
| I <sub>oz</sub> | 3-state OFF-state current | V <sub>I</sub> = V <sub>CC</sub> or GND   | 5.5                    | –                     | –    | 0.25 | –    | 2.5        | –    | 10   | µA          |      |
| I <sub>LI</sub> | input leakage current     | V <sub>I</sub> = V <sub>CC</sub> or GND   | 5.5                    | –                     | –    | 0.1  | –    | 1.0        | –    | 2.0  | µA          |      |
| I <sub>CC</sub> | quiescent supply current  | V <sub>I</sub> = V <sub>CC</sub> or GND;<br>I <sub>O</sub> = 0                    | 5.5                    | –                     | –    | 1.0  | –    | 10         | –    | 40   | µA          |      |
| C <sub>I</sub>  | input capacitance         |   |                        | –                     | 1.5  | 10   | –    | 10         | –    | 10   | pF          |      |

## Bus buffer/line driver; 3-state

## 74AHC1G126; 74AHCT1G126

## Family 74AHCT1G

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| SYMBOL           | PARAMETER   | TEST CONDITIONS  |                     | T <sub>amb</sub> (°C) |      |      |            |      |             |      | UNIT |
|------------------|---|--|---------------------|-----------------------|------|------|------------|------|-------------|------|------|
|                  |   | OTHER  | V <sub>CC</sub> (V) | 25                    |      |      | -40 to +85 |      | -40 to +125 |      |      |
|                  |   |  |                     | MIN.                  | TYP. | MAX. | MIN.       | MAX. | MIN.        | MAX. |      |
| V <sub>IH</sub>  | HIGH-level input voltage                          |  | 4.5 to 5.5          | 2.0                   | –    | –    | 2.0        | –    | 2.0         | –    | V    |
| V <sub>IL</sub>  | LOW-level input voltage                           |  | 4.5 to 5.5          | –                     | –    | 0.8  | –          | 0.8  | –           | 0.8  | V    |
| V <sub>OH</sub>  | HIGH-level output voltage                         | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = –50 µA         | 4.5                 | 4.4                   | 4.5  | –    | 4.4        | –    | 4.4         | –    | V    |
|                  |   | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = –8.0 mA        | 4.5                 | 3.94                  | –    | –    | 3.8        | –    | 3.70        | –    | V    |
| V <sub>OL</sub>  | LOW-level output voltage                          | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = 50 µA          | 4.5                 | –                     | 0    | 0.1  | –          | 0.1  | –           | 0.1  | V    |
|                  |   | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>I <sub>O</sub> = 8.0 mA         | 4.5                 | –                     | –    | 0.36 | –          | 0.44 | –           | 0.55 | V    |
| I <sub>OZ</sub>  | 3-state OFF-state current                         | V <sub>I</sub> = V <sub>CC</sub> or GND  | 5.5                 | –                     | –    | 0.25 | –          | 2.5  | –           | 10   | µA   |
| I <sub>LI</sub>  | input leakage current                             | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>                                      | 5.5                 | –                     | –    | 0.1  | –          | 1.0  | –           | 2.0  | µA   |
| I <sub>CC</sub>  | quiescent supply current                          | V <sub>I</sub> = V <sub>CC</sub> or GND;<br>I <sub>O</sub> = 0                           | 5.5                 | –                     | –    | 1.0  | –          | 10   | –           | 40   | µA   |
| ΔI <sub>CC</sub> | additional quiescent supply current per input pin | V <sub>I</sub> = 3.4 V;<br>other inputs at V <sub>CC</sub> or GND;<br>I <sub>O</sub> = 0 | 5.5                 | –                     | –    | 1.35 | –          | 1.5  | –           | 1.5  | mA   |
| C <sub>I</sub>   | input capacitance                                 |  |                     | –                     | 1.5  | 10   | –          | 10   | –           | 10   | pF   |

## Bus buffer/line driver; 3-state

## 74AHC1G126; 74AHCT1G126

## AC CHARACTERISTICS

## Type 74AHC1G126

Ground = 0 V;  $t_r = t_f \leq 3.0$  ns.

| SYMBOL   | PARAMETER                    | TEST CONDITIONS  |               | $T_{amb}$ (°C) |      |      |            |      |             | UNIT |      |
|--|------------------------------|------------------|---------------|----------------|------|------|------------|------|-------------|------|------|
|  |                              | WAVEFORMS        | $C_L$<br>(pF) | 25             |      |      | -40 to +85 |      | -40 to +125 |      |      |
|  |                              |                  |               | MIN.           | TYP. | MAX. | MIN.       | MAX. | MIN.        |      | MAX. |
| <b><math>V_{CC} = 3.0</math> to <math>3.6</math> V; note 1</b> |                              |                  |               |                |      |      |            |      |             |      |      |
| $t_{PHL}/t_{PLH}$  | propagation delay<br>A to Y  | see Figs 5 and 7 | 15            | –              | 4.4  | 8.0  | 1.0        | 9.5  | 1.0         | 10.0 | ns   |
| $t_{PZH}/t_{PZL}$  | propagation delay<br>OE to Y | see Figs 6 and 7 | 15            | –              | 4.9  | 8.0  | 1.0        | 9.5  | 1.0         | 10.0 | ns   |
| $t_{PHZ}/t_{PLZ}$  | propagation delay<br>OE to Y | see Figs 6 and 7 | 15            | –              | 6.3  | 9.7  | 1.0        | 11.5 | 1.0         | 12.5 | ns   |
| $t_{PHL}/t_{PLH}$  | propagation delay<br>A to Y  | see Figs 5 and 7 | 50            | –              | 6.3  | 11.5 | 1.0        | 13.0 | 1.0         | 14.5 | ns   |
| $t_{PZH}/t_{PZL}$  | propagation delay<br>OE to Y | see Figs 6 and 7 | 50            | –              | 7.0  | 11.5 | 1.0        | 13.0 | 1.0         | 14.5 | ns   |
| $t_{PHZ}/t_{PLZ}$  | propagation delay<br>OE to Y | see Figs 6 and 7 | 50            | –              | 9.0  | 13.2 | 1.0        | 15.0 | 1.0         | 16.5 | ns   |
| <b><math>V_{CC} = 4.5</math> to <math>5.5</math> V; note 2</b> |                              |                  |               |                |      |      |            |      |             |      |      |
| $t_{PHL}/t_{PLH}$  | propagation delay<br>A to Y  | see Figs 5 and 7 | 15            | –              | 3.4  | 5.5  | 1.0        | 6.5  | 1.0         | 7.0  | ns   |
| $t_{PZH}/t_{PZL}$  | propagation delay<br>OE to Y | see Figs 6 and 7 | 15            | –              | 3.6  | 5.6  | 1.0        | 6.3  | 1.0         | 7.0  | ns   |
| $t_{PHZ}/t_{PLZ}$  | propagation delay<br>OE to Y | see Figs 6 and 7 | 15            | –              | 4.3  | 6.8  | 1.0        | 8.0  | 1.0         | 8.5  | ns   |
| $t_{PHL}/t_{PLH}$  | propagation delay<br>A to Y  | see Figs 5 and 7 | 50            | –              | 4.7  | 7.5  | 1.0        | 8.5  | 1.0         | 9.5  | ns   |
| $t_{PZH}/t_{PZL}$  | propagation delay<br>OE to Y | see Figs 6 and 7 | 50            | –              | 5.4  | 8.0  | 1.0        | 9.0  | 1.0         | 9.5  | ns   |
| $t_{PHZ}/t_{PLZ}$  | propagation delay<br>OE to Y | see Figs 6 and 7 | 50            | –              | 6.1  | 8.8  | 1.0        | 10.0 | 1.0         | 11.0 | ns   |

## Notes

1. Typical values are measured at  $V_{CC} = 3.3$  V.
2. Typical values are measured at  $V_{CC} = 5.0$  V.



Bus buffer/line driver; 3-state

74AHC1G126; 74AHCT1G126

Type 74AHCT1G126

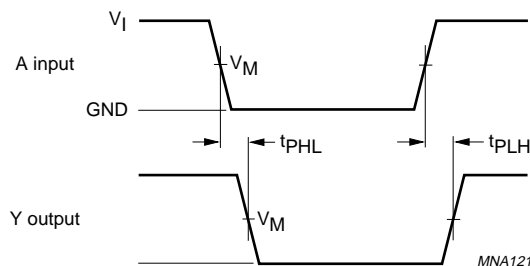
Ground = 0 V;  $t_r = t_f \leq 3.0$  ns.

| SYMBOL                                       | PARAMETER                    | TEST CONDITIONS  |                     | T <sub>amb</sub> (°C) |      |      |            |      |             | UNIT |      |
|--|------------------------------|------------------|---------------------|-----------------------|------|------|------------|------|-------------|------|------|
|  |                              | WAVEFORMS        | C <sub>L</sub> (pF) | 25                    |      |      | -40 to +85 |      | -40 to +125 |      |      |
|  |                              |                  |                     | MIN.                  | TYP. | MAX. | MIN.       | MAX. | MIN.        |      | MAX. |
| <b>V<sub>CC</sub> = 4.5 to 5.5 V; note 1</b> |                              |                  |                     |                       |      |      |            |      |             |      |      |
| t <sub>PHL</sub> /t <sub>PLH</sub>           | propagation delay<br>A to Y  | see Figs 5 and 7 | 15                  | –                     | 3.4  | 5.5  | 1.0        | 6.5  | 1.0         | 7.0  | ns   |
| t <sub>PZH</sub> /t <sub>PZL</sub>           | propagation delay<br>OE to Y | see Figs 6 and 7 | 15                  | –                     | 3.4  | 5.6  | 1.0        | 6.3  | 1.0         | 6.5  | ns   |
| t <sub>PHZ</sub> /t <sub>PLZ</sub>           | propagation delay<br>OE to Y | see Figs 6 and 7 | 15                  | –                     | 4.0  | 6.8  | 1.0        | 8.0  | 1.0         | 8.5  | ns   |
| t <sub>PHL</sub> /t <sub>PLH</sub>           | propagation delay<br>A to Y  | see Figs 5 and 7 | 50                  | –                     | 4.7  | 7.5  | 1.0        | 8.5  | 1.0         | 9.5  | ns   |
| t <sub>PZH</sub> /t <sub>PZL</sub>           | propagation delay<br>OE to Y | see Figs 6 and 7 | 50                  | –                     | 4.8  | 8.0  | 1.0        | 9.0  | 1.0         | 9.0  | ns   |
| t <sub>PHZ</sub> /t <sub>PLZ</sub>           | propagation delay<br>OE to Y | see Figs 6 and 7 | 50                  | –                     | 5.7  | 8.8  | 1.0        | 10.0 | 1.0         | 11.5 | ns   |

Note

1. Typical values are measured at V<sub>CC</sub> = 5 V.

AC WAVEFORMS

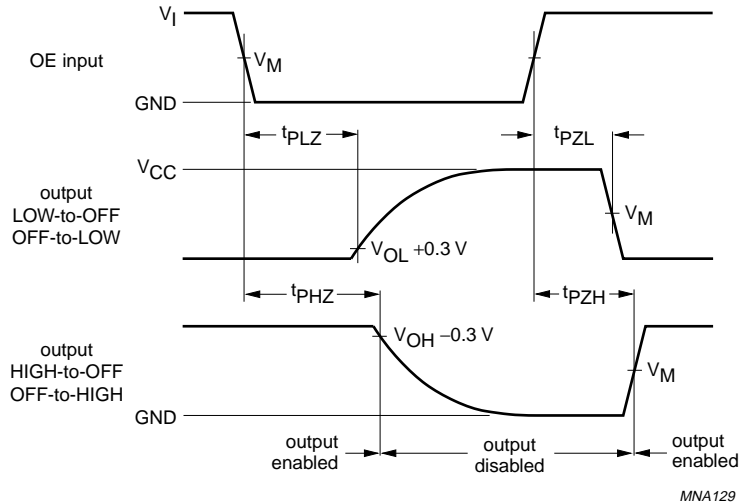


| FAMILY | V <sub>I</sub> INPUT REQUIREMENTS | V <sub>M</sub> INPUT | V <sub>M</sub> OUTPUT |
|--------|-----------------------------------|----------------------|-----------------------|
| AHC1G  | GND to V <sub>CC</sub>            | 50% V <sub>CC</sub>  | 50% V <sub>CC</sub>   |
| AHCT1G | GND to 3.0 V                      | 1.5 V                | 50% V <sub>CC</sub>   |

Fig.5 The input (A) to output (Y) propagation delays.

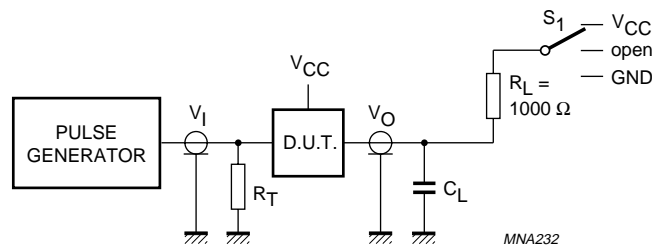
Bus buffer/line driver; 3-state

74AHC1G126; 74AHCT1G126



| FAMILY | V <sub>I</sub> INPUT REQUIREMENTS | V <sub>M</sub> INPUT | V <sub>M</sub> OUTPUT |
|--------|-----------------------------------|----------------------|-----------------------|
| AHC1G  | GND to V <sub>CC</sub>            | 50% V <sub>CC</sub>  | 50% V <sub>CC</sub>   |
| AHCT1G | GND to 3.0 V                      | 1.5 V                | 50% V <sub>CC</sub>   |

Fig.6 The 3-state enable and disable times.



| TEST                               | S <sub>1</sub>  |
|------------------------------------|-----------------|
| t <sub>PLH</sub> /t <sub>PHL</sub> | open            |
| t <sub>PLZ</sub> /t <sub>PZL</sub> | V <sub>CC</sub> |
| t <sub>PHZ</sub> /t <sub>PZH</sub> | GND             |

Definitions for test circuit:

C<sub>L</sub> = load capacitance including jig and probe capacitance (See Chapter "AC characteristics").

R<sub>L</sub> = load resistance.

R<sub>T</sub> = termination resistance should be equal to the output impedance Z<sub>o</sub> of the pulse generator.

Fig.7 Load circuitry for switching times.

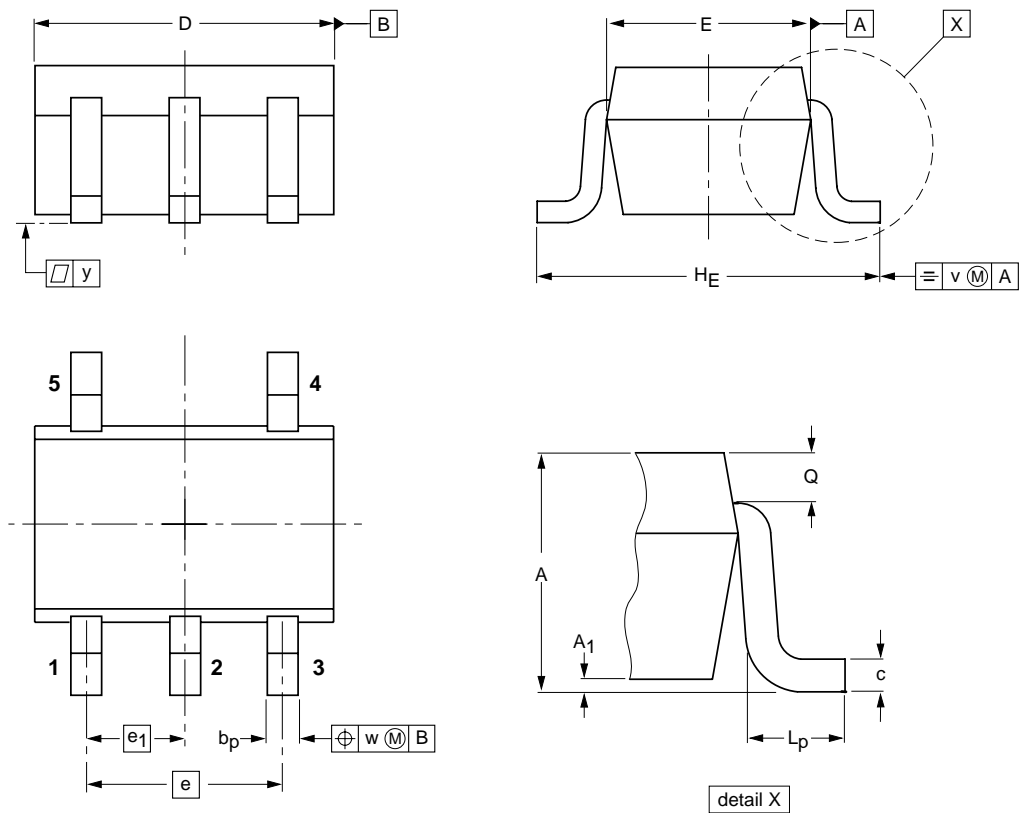
Bus buffer/line driver; 3-state

74AHC1G126; 74AHCT1G126

PACKAGE OUTLINES

Plastic surface mounted package; 5 leads

SOT353



DIMENSIONS (mm are the original dimensions)

| UNIT | A          | A <sub>1</sub><br>max | bp           | c            | D          | E <sup>(2)</sup> | e   | e <sub>1</sub> | H <sub>E</sub> | L <sub>p</sub> | Q            | v   | w   | y   |
|------|------------|-----------------------|--------------|--------------|------------|------------------|-----|----------------|----------------|----------------|--------------|-----|-----|-----|
| mm   | 1.1<br>0.8 | 0.1                   | 0.30<br>0.20 | 0.25<br>0.10 | 2.2<br>1.8 | 1.35<br>1.15     | 1.3 | 0.65           | 2.2<br>2.0     | 0.45<br>0.15   | 0.25<br>0.15 | 0.2 | 0.2 | 0.1 |

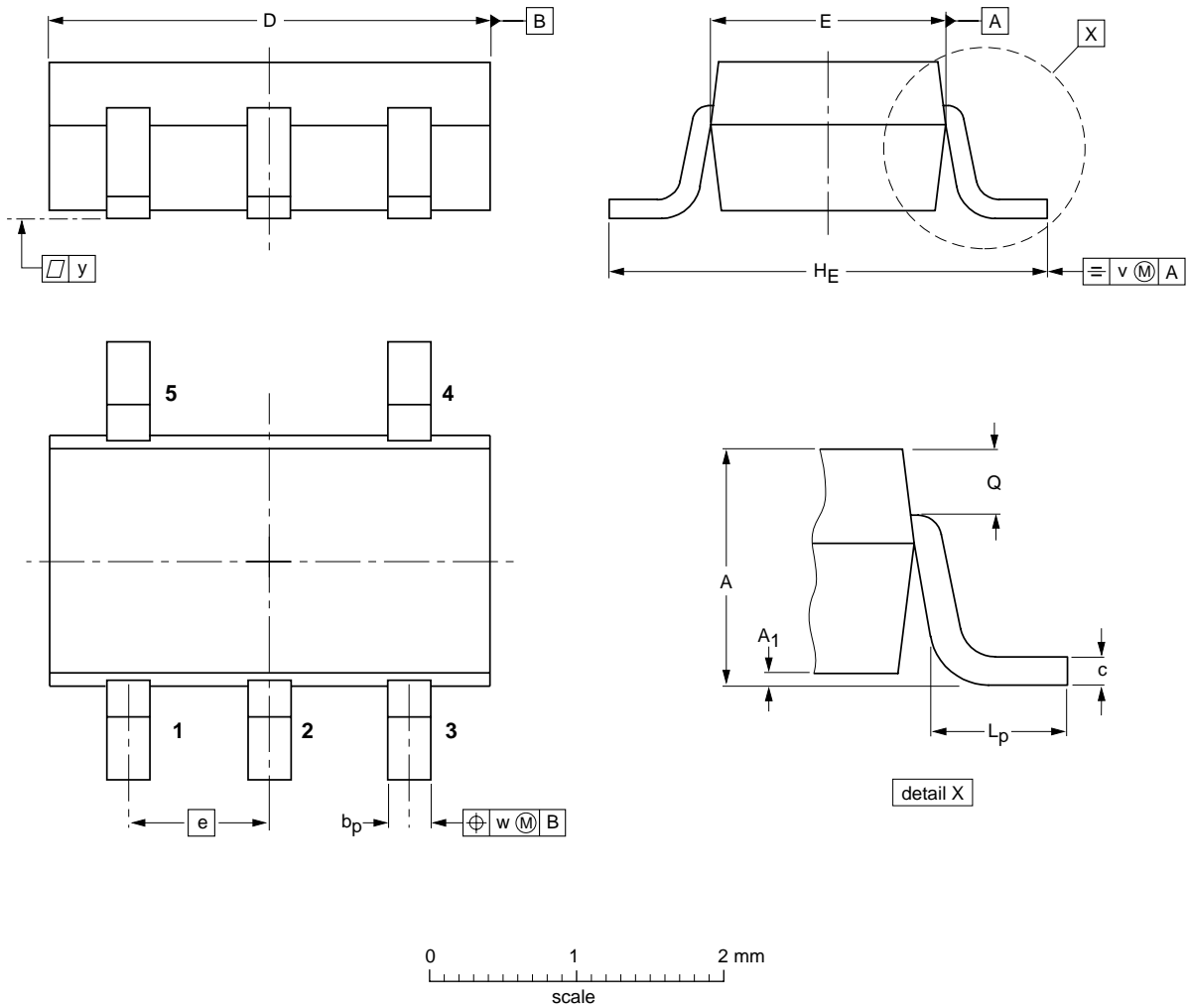
| OUTLINE<br>VERSION | REFERENCES |       |        |  | EUROPEAN<br>PROJECTION | ISSUE DATE |
|--------------------|------------|-------|--------|--|------------------------|------------|
|                    | IEC        | JEDEC | EIAJ   |  |                        |            |
| SOT353             |            |       | SC-88A |  |                        | 97-02-28   |

Bus buffer/line driver; 3-state

74AHC1G126; 74AHCT1G126

Plastic surface mounted package; 5 leads

SOT753



DIMENSIONS (mm are the original dimensions)

| UNIT | A          | A <sub>1</sub> | b <sub>p</sub> | c            | D          | E          | e    | H <sub>E</sub> | L <sub>p</sub> | Q            | v   | w   | y   |
|------|------------|----------------|----------------|--------------|------------|------------|------|----------------|----------------|--------------|-----|-----|-----|
| mm   | 1.1<br>0.9 | 0.100<br>0.013 | 0.40<br>0.25   | 0.26<br>0.10 | 3.1<br>2.7 | 1.7<br>1.3 | 0.95 | 3.0<br>2.5     | 0.6<br>0.2     | 0.33<br>0.23 | 0.2 | 0.2 | 0.1 |

| OUTLINE VERSION | REFERENCES |       |        |  | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|-------|--------|--|---------------------|------------|
|                 | IEC        | JEDEC | JEITA  |  |                     |            |
| SOT753          |            |       | SC-74A |  |                     | 02-04-16   |

## Bus buffer/line driver; 3-state

## 74AHC1G126; 74AHCT1G126

### SOLDERING

#### Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

#### Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 220 °C for thick/large packages, and below 235 °C for small/thin packages.

#### Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

#### Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

## Bus buffer/line driver; 3-state

## 74AHC1G126; 74AHCT1G126

## Suitability of surface mount IC packages for wave and reflow soldering methods

| PACKAGE <sup>(1)</sup>   | SOLDERING METHOD                  |                       |
|--|-----------------------------------|-----------------------|
|  | WAVE                              | REFLOW <sup>(2)</sup> |
| BGA, LBGA, LFBGA, SQFP, TFBGA, VFBGA                             | not suitable                      | suitable              |
| HBCC, HBGA, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, HVQFN, HVSON, SMS | not suitable <sup>(3)</sup>       | suitable              |
| PLCC <sup>(4)</sup> , SO, SOJ                                    | suitable                          | suitable              |
| LQFP, QFP, TQFP  | not recommended <sup>(4)(5)</sup> | suitable              |
| SSOP, TSSOP, VSO   | not recommended <sup>(6)</sup>    | suitable              |

## Notes

- For more detailed information on the BGA packages refer to the “(LF)BGA Application Note” (AN01026); order a copy from your Philips Semiconductors sales office.
- All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the “Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods”.
- These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.
- If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
- Wave soldering is suitable for LQFP, TQFP and QFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
- Wave soldering is suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

## Bus buffer/line driver; 3-state

## 74AHC1G126; 74AHCT1G126

## DATA SHEET STATUS

| DATA SHEET STATUS <sup>(1)</sup> | PRODUCT STATUS <sup>(2)</sup> | DEFINITIONS  |
|----------------------------------|-------------------------------|--|
| Objective data                   | Development                   | This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.  |
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For additional information please visit <http://www.semiconductors.philips.com>. Fax: +31 40 27 24825

For sales offices addresses send e-mail to: [sales.addresses@www.semiconductors.philips.com](mailto:sales.addresses@www.semiconductors.philips.com).

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Printed in The Netherlands

613508/04/pp16

Date of release: 2002 Jun 06

Document order number: 9397 750 09707

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